GooLED

GooLED-NIC-4850 Pin Fin Heat Sink Φ48mm for Nichia

Features VS Benefits

* The GooLED-NIC-4850 Nichia Pin Fin LED Heat Sinks are specifically designed for
  luminaires using the Nichia LED engines.
* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and
  thermal performance matching the lumen packages.
* For spotlight and downlight designs from 500 to 1,600 lumen.
* Thermal resistance range Rth 5.0°C/W.
* Modular design with mounting holes foreseen for direct mounting of Nichia COB series.
* Diameter 48.0mm - standard height 50.0mm, Other heights on request.
* Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

* Below you find an overview of Nichia COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
* In this way mechanical after work and related costs can be avoided, and lighting designers
  can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

Nichia LED Modules directly Mounting Options

Nichia COB LED modules name:

NFCWL036B;
NFCLL036B;
NFCWL060B;
NFCLL060B;

With the Zhaga Book 3 Holders:
Ideal Holder:50-2100NC;
TE LED Holder:2213382-2;
Direct mounting with machine screws M3x6.5mm, Green indicator marks.
With the LEDiL products:
Lena series: CN14xxx;   C13xxx;   C12xxx;
Ronda series: FN15xxx-xx;

Nichia COB LED modules name:
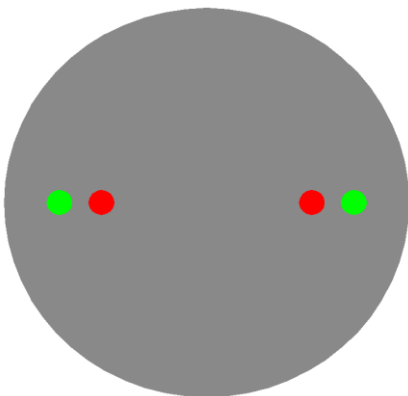
NVCWL024Z;
NVCLL024Z;
NVNWS007Z;
NJCWS024Z;

With the Zhaga Book 11 Holders:
BJB holder:47.319.6180.50;
TE LED Holder:2213118-1;
Direct mounting with machine screws M3x8mm, Red indicator marks.
With the LEDiL products:
Lena series: CN14xxx;   C13xxx;   C12xxx;
Ronda series: FN15xxx-xx;

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Mounting Options and Drawings & Dimensions

Example:GooLED-NIC-4850-B-1,2

Example:GooLED-NIC-48 [1] - [2] - [3]

[1] **Height (mm)**

[2] **Anodising Color**

    B-Black

    C-Clear

    Z-Custom

[3] **Mounting Options - see graphics for**

   **details Combinations available**

    Ex.order code - 12

    means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.

- For specific mechanical adaptations please contact MingfaTech.

- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Lena series	Ronda series			
N	/	None	None	None	None	None	None
1	NVCWL024Z; NVCLL024Z; NVNWS007Z; NJCWS024Z;	BJB Holder 47.319.6180.50 — TE Holder 2213118-1	CN14xxx; C13xxx; C12xxx;	FN15xxx-xx	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
2	NFCWL036B; NFCLL036B; NFCWL060B; NFCLL060B;	Ideal Holder 50-2100NC — TE Holder 2213382-2			M3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)

Mingfa Tech

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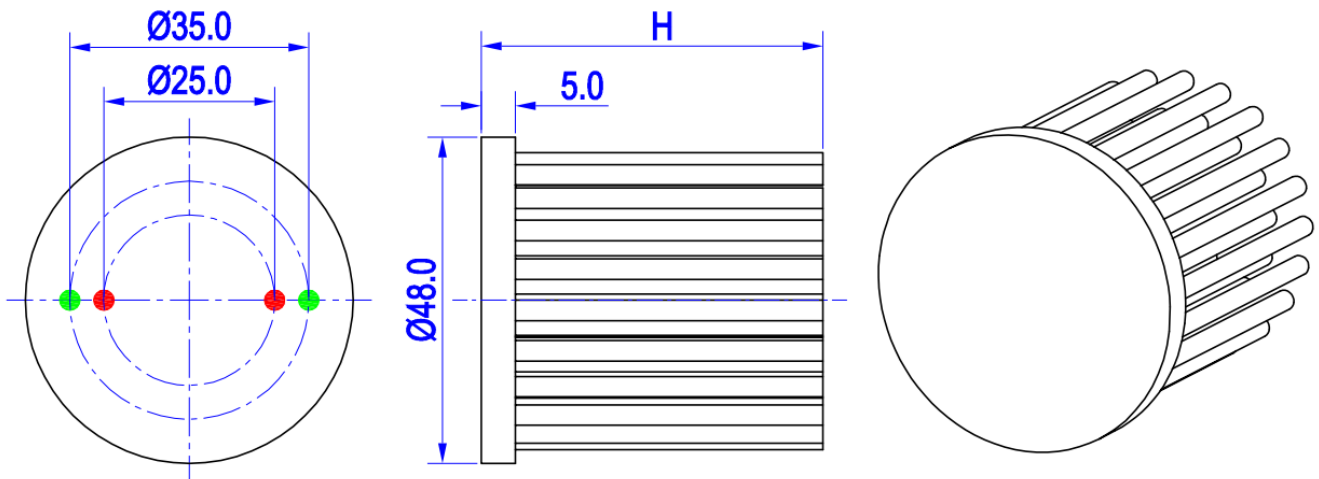
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The product deta table

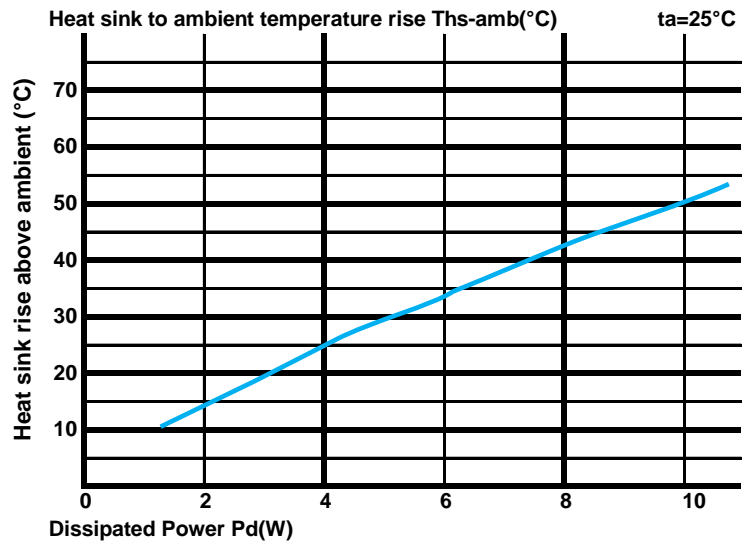| Model No.	GooLED-NIC-4850
Heatsink Size	Φ48xH50mm
Heatsink Material	AL1070
Finish	Black Anodized
Weight (g)	64.0
Dissipated power (Ths-amb,50℃)	10.0 (W)
Cooling surface area (mm²)	24285
Thermal Resistance (Rhs-amb)	5.0 (°C/W)

The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

  Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		GooLED-NIC-4850	
Dissipated Power Pd(W)	2.0	7.00	14.0
	4.0	6.25	25.0
	6.0	5.67	34.0
	8.0	5.38	43.0
	10.0	5.00	50.0

Heat sink to ambient temperature rise Ths-amb(°C)   ta=25°C

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

 MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

 Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.

*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

  Geometric shapes are different, the thermal resistance is different. Formula: θ ＝(Ths－Ta)/Pd

  θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ;   Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

  $T_{junction}＝(R_{junction-case}＋R_{case-ambient})·Pd＋T_{ambient}$